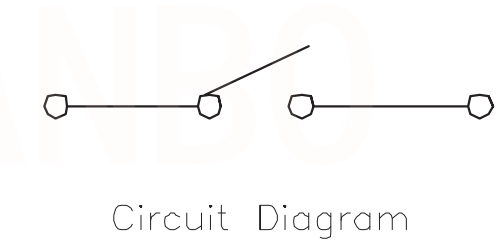
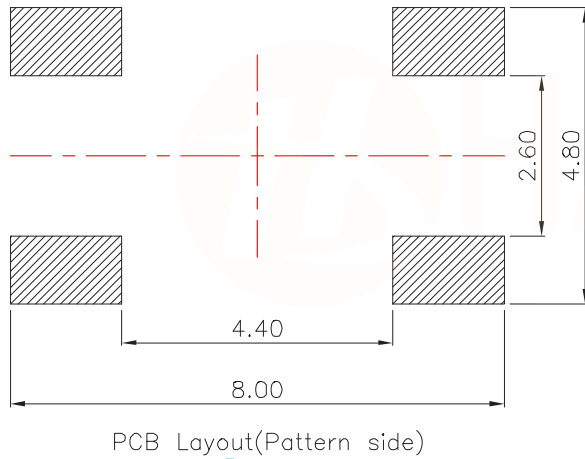


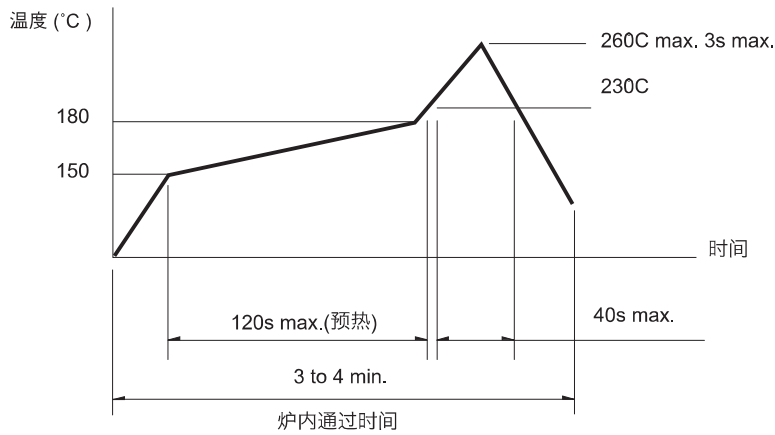
▶ ▶ ▶ 线路图/Circuit diagram



▶ ▶ ▶ 焊接条件/Welding conditions

■ 回流焊时/During reflow soldering

适用于表面贴装型温度分布/Applicable to surface mount temperature distribution



注/notes

- 关于详细条件, 请于本公司的产品规格书进行确认。
Please confirm the detailed conditions in our product specification
- 根据贴面焊槽的种类, 条件不同结果不同, 请事先充分进行确认之后使用。
According to the type of veneer welding groove and different conditions, the results are different. Please fully confirm before using.

■ 自动浸焊式/Automatic dip welding

| 项目 | 条件 |
|--------|--------------------------|
| 助焊剂附着量 | 不附着于零部件贴装面的程度 |
| 预热温度 | 印刷电路板焊接面的周围温度 100°C max. |
| 预热温度时间 | 60s max. |
| 焊接温度 | 260°C max. |
| 焊接浸渍时间 | 5s max. |
| 焊接次数 | 2 times max. |

注/notes

- 请不要从轻触开关上面浸入助焊剂。
Do not immerse the flux on the touch switch
- 请不要事前在开关端子及印刷电路板的零部件贴装面上涂助焊剂。
Please do not apply flux on the mounting surface of switch terminals and printed circuit board components in advance
- 进行第 2 次焊接时, 应在开关回复到常温之后进行。
The second welding shall be carried out after the switch returns to normal temperature.

■ 手焊式/Hand welded

| 项目 | 条件 |
|--------|------------|
| 焊接温度 | 350°C max. |
| 焊接浸渍时间 | 3s max. |
| 焊剂斗容量 | 60W max. |